

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5729094

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the TYPOGRAPHICAL ERROR IN 1ST INVENTOR'S NAME previously recorded on Reel 031129 Frame 0423. Assignor(s) hereby confirms the ASSIGNMENT OF ASSIGNORS INTEREST.

CONVEYING PARTY DATA

Name	Execution Date
KUO-CHENG CHIANG	09/18/2019
JIUN-JIA HUANG	09/18/2019
CHAO-HSIUNG WANG	09/18/2019
CHI-WEN LIU	09/18/2019

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	8, Li-Hsin Rd. 6, Hsinchu Science Park
City:	Hsinchu
State/Country:	TAIWAN
Postal Code:	300-78

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14017036

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	TSM13-0460
NAME OF SUBMITTER:	MARANDA BRALLEY
SIGNATURE:	/Maranda Bralley/
DATE SIGNED:	09/20/2019

Total Attachments: 6

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PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Kuo-Cheng Ching	08/29/2013
Jiun-Jia Huang	08/29/2013
Chao-Hsiung Wang	09/02/2013
Chi-Wen Liu	08/30/2013
RECEIVING PARTY DATA	
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77 R.O.C.
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14017036

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ATTORNEY DOCKET NUMBER:	TSM13-0460
NAME OF SUBMITTER:	Kasey Edwards
Signature:	/Kasey Edwards/
Date:	09/03/2013
Total Attachments: 1 source=TSM13-0460_Assignment#page1.tif	
RECEIPT INFORMATION	
EPAS ID:	PAT2525639
Receipt Date:	09/03/2013
Fee Amount:	\$40

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ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<i>FinFET Device and Method of Fabricating Same</i>			
SIGNATURE OF INVENTOR AND NAME	✓ <i>Kuo-Cheng Ching</i> Kuo-Cheng Ching	✓ <i>Jiun-Jia Huang</i> Jiun-Jia Huang	✓ <i>Chao-Hsiung Wang</i> Chao-Hsiung Wang	✓ <i>Chi-Wen Liu</i> Chi-Wen Liu
DATE	✓ <i>2013/8/28</i>	✓ <i>2013/8/29</i>	✓ <i>2013/9/12</i>	✓ <i>2013/8/30</i>
RESIDENCE (City, County, State)	Zhubei City, Taiwan	Hsin-Chu, Taiwan	Hsin-Chu, Taiwan	Hsin-Chu, Taiwan

ATTORNEY DOCKET NO.
TSM13-0460

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, with its principal office at 8, Li-Hsin Rd. 6 Hsinchu Science Park, Hsinchu 300-78, Taiwan, is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	FinFET Device and Method of Fabricating Same			
SIGNATURE OF INVENTOR AND NAME	<i>Kuo-Cheng Chiang</i> Kuo-Cheng Chiang	<i>Jiun-Jia Huang</i> Jiun-Jia Huang	<i>Chao-Hsiung Wang</i> Chao-Hsiung Wang	<i>Chi-Wen Liu</i> Chi-Wen Liu
DATE	2019/9/18	2019/9/18	2019/9/18	2019/9/18
RESIDENCE	Zhubei City, Taiwan	Beigang Township, Taiwan	Hsin-Chu City, Taiwan	Hsinchu, Taiwan